



APPLICATION
FOR
UNITED STATES LETTERS PATENT

Applicant

Kangguo Cheng, et al.

For

"Method and Structure of Vertical
Strained Silicon Devices"

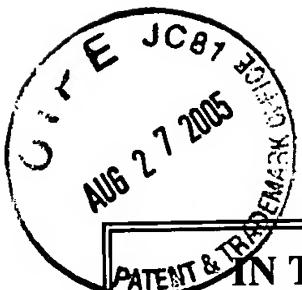
Docket

FIS920030221US1

INTERNATIONAL BUSINESS
MACHINES CORPORATION
ARMONK, NEW YORK 10504

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE
UNITED STATES POSTAL SERVICE AS EXPRESS MAIL IN AN ENVELOPE ADDRESSED
TO: U.S. PATENT AND TRADEMARK OFFICE, P.O. BOX 1450, ALEXANDRIA, VA.
22313. THE APPLICANT AND/OR ATTORNEY REQUESTS THE DATE OF DEPOSIT AS
THE FILING DATE.

Express Mail No: ER857358843US1
Date of Deposit: August 27, 2005
Name of Person Making Deposit: Eric W. Petraske
Signature: *EW Petraske*



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| | |
|---|---|
| <u>In re application of:</u> Kangguo Cheng | <u>Filed:</u> 09/16/2003 <u>Examiner:</u> K. L. Rose |
| <u>Serial No.</u> 10/605227 | <u>Group Art Unit:</u> 2822 |
| <u>Title:</u> Method and Structure of Vertical Strained Silicon Devices | <u>Docket #:</u> FIS920030221US1 |

PRELIMINARY AMENDMENT

Commissioner of Patents & Trademarks
Alexandria, VA 22313

Sir:

Please amend the above identified application as follows: